

Title (en)

A mounting assembly for inductors and method of producing the same

Title (de)

Zusammenbau für Induktoren und Verfahren zur Herstellung

Title (fr)

Ensemble de montage pour les inductances et son procédé de fabrication

Publication

EP 1647999 A1 20060419 (EN)

Application

EP 04425772 A 20041013

Priority

EP 04425772 A 20041013

Abstract (en)

A mounting assembly of an inductor (1) includes: a moulded inductor body (bobbin - 2) of an electrically insulating material having an end face (20b) with one or more integrally moulded pins (200) protruding from the end face (20b), a wire winding (3) around the body (2), the wire of the winding having at least one end (30) wound around the a respective one of the integrally moulded pins (200) protruding therefrom, and a mass of soldering material (4) securing the end(s) of the wire (3) wound around the respective integrally moulded pin (200), whereby the soldering material (4) provides electrical contact to the end (30) of the wire.

IPC 8 full level

H01F 5/04 (2006.01); **H01F 27/32** (2006.01); **H01F 41/06** (2006.01)

CPC (source: EP)

H01F 5/04 (2013.01); **H01F 41/076** (2016.01); **H01F 2005/043** (2013.01); **H01F 2027/297** (2013.01)

Citation (search report)

- [X] US 4774756 A 19881004 - DETHIENNE HENRI-PIERRE Y [BE]
- [X] US 5696477 A 19971209 - YAMAMORI MASAYA [JP], et al
- [A] WO 03069640 A1 20030821 - SIEMENS AG OESTERREICH [AT], et al

Cited by

US2012039040A1

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DOCDB simple family (publication)

EP 1647999 A1 20060419; **EP 1647999 B1 20080319**; AT E389942 T1 20080415; CN 1760999 A 20060419; CN 1760999 B 20110112; DE 602004012566 D1 20080430; DE 602004012566 T2 20090416

DOCDB simple family (application)

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